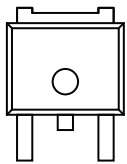


PRODUCT SUMMARY	
V _{DS} (V)	50
R _{DS(on)} (Ω) at V _{GS} = 10 V	0.011
R _{DS(on)} (Ω) at V _{GS} = 4.5 V	0.015
I _D (A)	50
Configuration	Single

FEATURES

- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- 100 % R_g and UIS Tested
- AEC-Q101 Qualified^d
- Material categorization:
For definitions of compliance please see
www.freescale.net.cn

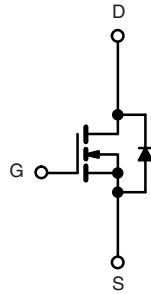
TO-252



G D S

Top View

Drain Connected to Tab



N-Channel MOSFET

ORDERING INFORMATION	
Package	TO-252
Lead (Pb)-free and Halogen-free	SQD50N05-11L-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DS}	50	V
Gate-Source Voltage	V _{GS}	± 20	
Continuous Drain Current	I _D	T _C = 25 °C ^a	50
		T _C = 125 °C	32
Continuous Source Current (Diode Conduction) ^a	I _S	50	A
Pulsed Drain Current ^b	I _{DM}	200	
Single Pulse Avalanche Energy	E _{AS}	101	
Single Pulse Avalanche Current	I _{AS}	45	
Maximum Power Dissipation ^b	P _D	T _C = 25 °C	75
		T _C = 125 °C	25
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to + 175	°C

THERMAL RESISTANCE RATINGS			
PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-Ambient	R _{thJA}	60	°C/W
Junction-to-Case (Drain)	R _{thJC}	2.0	

Notes

- Package limited.
- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %.
- When mounted on 1" square PCB (FR-4 material).
- Parametric verification ongoing.

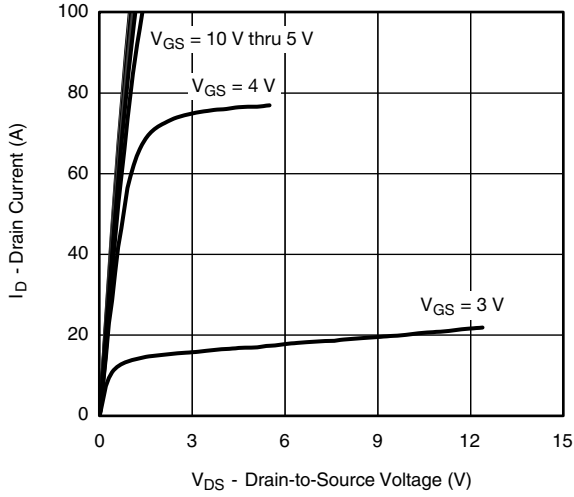
SPECIFICATIONS ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		50	-	-	V
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		1.5	2.0	2.5	
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0\text{ V}$	$V_{DS} = 50\text{ V}$	-	-	1.0	μA
		$V_{GS} = 0\text{ V}$	$V_{DS} = 50\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	-	50	
		$V_{GS} = 0\text{ V}$	$V_{DS} = 50\text{ V}, T_J = 175\text{ }^\circ\text{C}$	-	-	250	
On-State Drain Current ^a	$I_{D(on)}$	$V_{GS} = 10\text{ V}$	$V_{DS} \geq 5\text{ V}$	50	-	-	A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 45\text{ A}$	-	0.009	0.011	Ω
		$V_{GS} = 10\text{ V}$	$I_D = 45\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	-	0.020	
		$V_{GS} = 10\text{ V}$	$I_D = 45\text{ A}, T_J = 175\text{ }^\circ\text{C}$	-	-	0.024	
		$V_{GS} = 4.5\text{ V}$	$I_D = 20\text{ A}$	-	-	0.015	
Forward Transconductance ^b	g_{fs}	$V_{DS} = 15\text{ V}, I_D = 30\text{ A}$		-	58	-	S
Dynamic^b							
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	-	1685	2106	pF
Output Capacitance	C_{oss}			-	345	430	
Reverse Transfer Capacitance	C_{rss}			-	144	180	
Total Gate Charge ^c	Q_g	$V_{GS} = 10\text{ V}$	$V_{DS} = 25\text{ V}, I_D = 43\text{ A}$	-	34.6	52	nC
Gate-Source Charge ^c	Q_{gs}			-	5.5	9	
Gate-Drain Charge ^c	Q_{gd}			-	9.1	14	
Gate Resistance	R_g	$f = 1\text{ MHz}$		1.3	2.6	3.9	Ω
Turn-On Delay Time ^c	$t_{d(on)}$	$V_{DD} = 25\text{ V}, R_L = 0.6\text{ }\Omega$ $I_D \cong 43\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$		-	8.5	13	ns
Rise Time ^c	t_r			-	11.5	18	
Turn-Off Delay Time ^c	$t_{d(off)}$			-	22.5	34	
Fall Time ^c	t_f			-	7.5	12	
Source-Drain Diode Ratings and Characteristics^b							
Pulsed Current ^a	I_{SM}			-	-	200	A
Forward Voltage	V_{SD}	$I_F = 45\text{ A}, V_{GS} = 0\text{ V}$		-	0.95	1.5	V

Notes

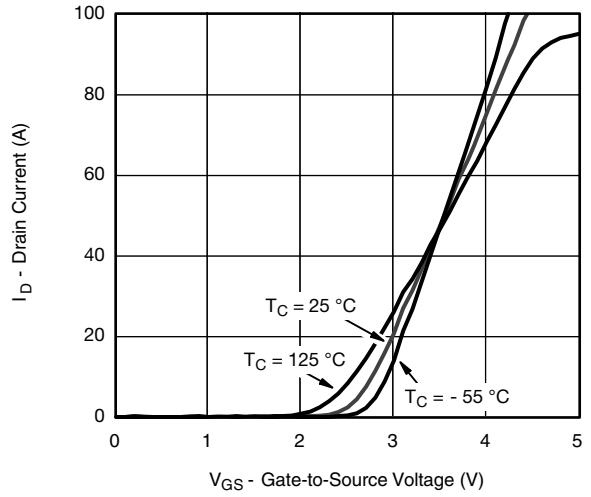
- Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

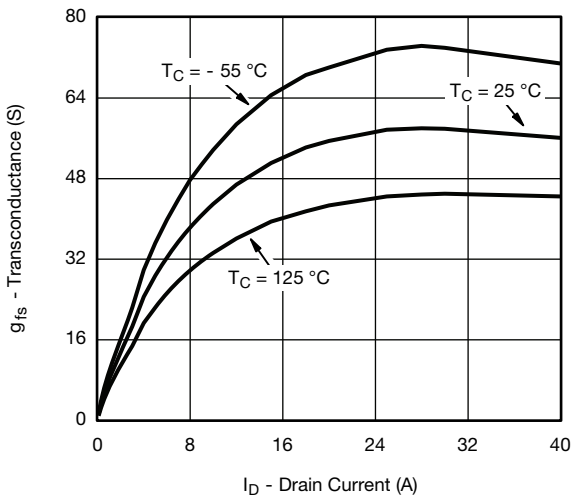
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



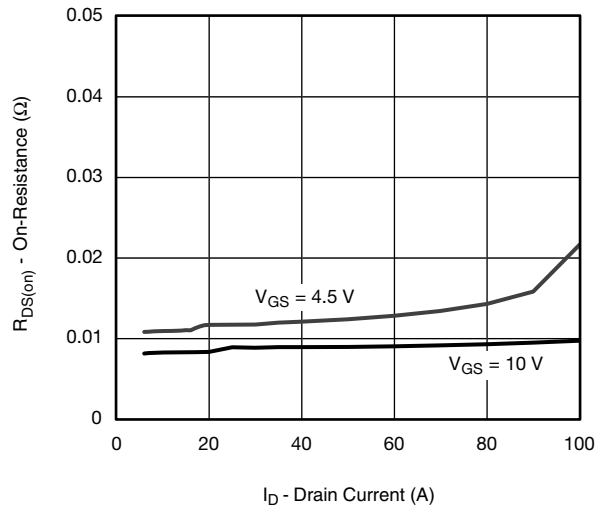
Output Characteristics



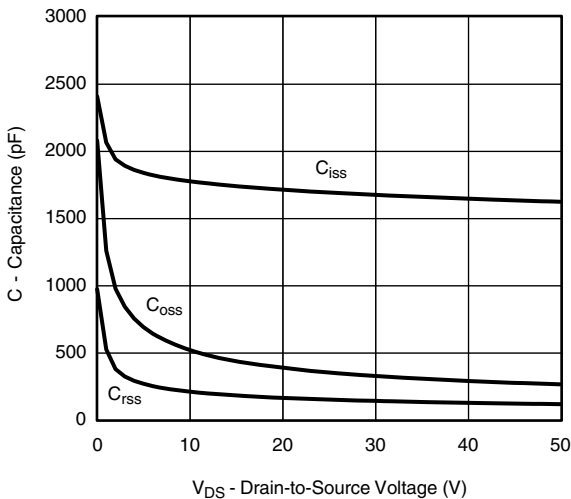
Transfer Characteristics



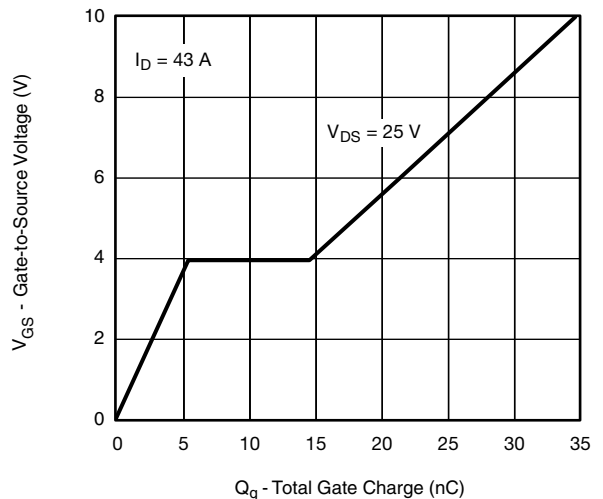
Transconductance



On-Resistance vs. Drain Current

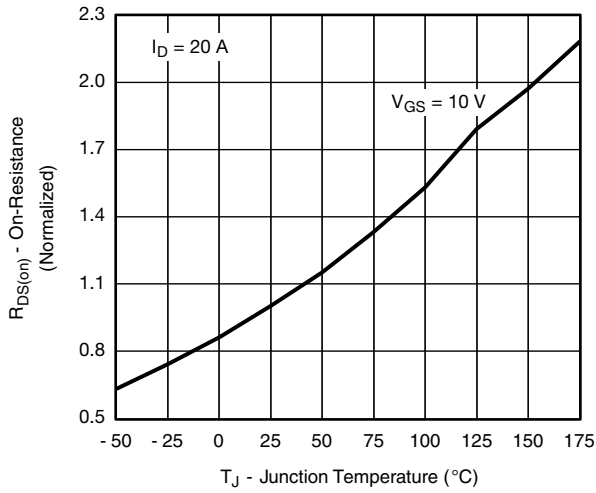


Capacitance

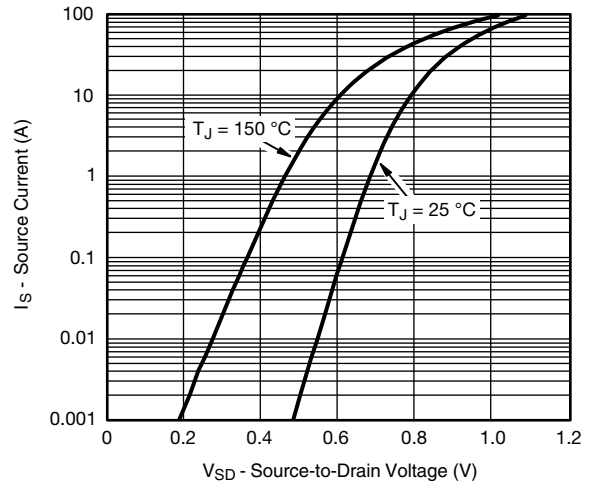


Gate Charge

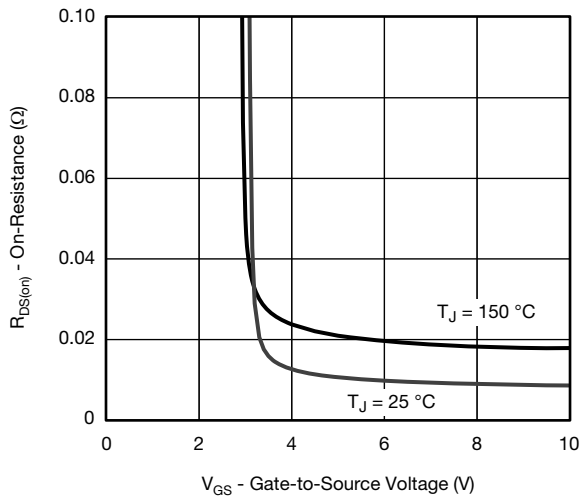
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



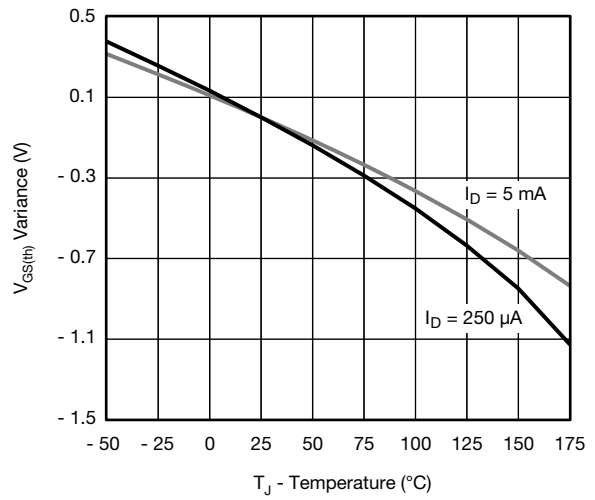
On-Resistance vs. Junction Temperature



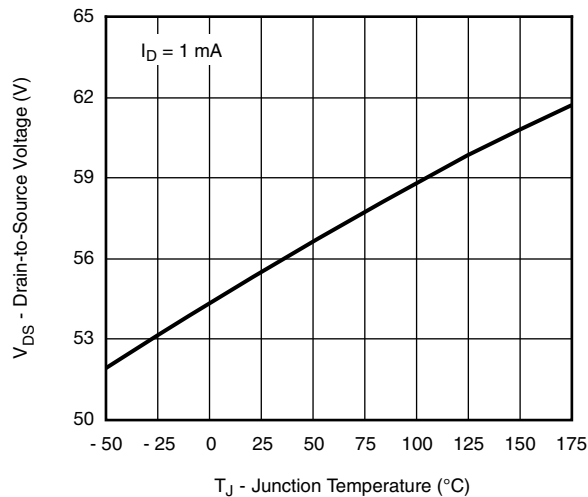
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage

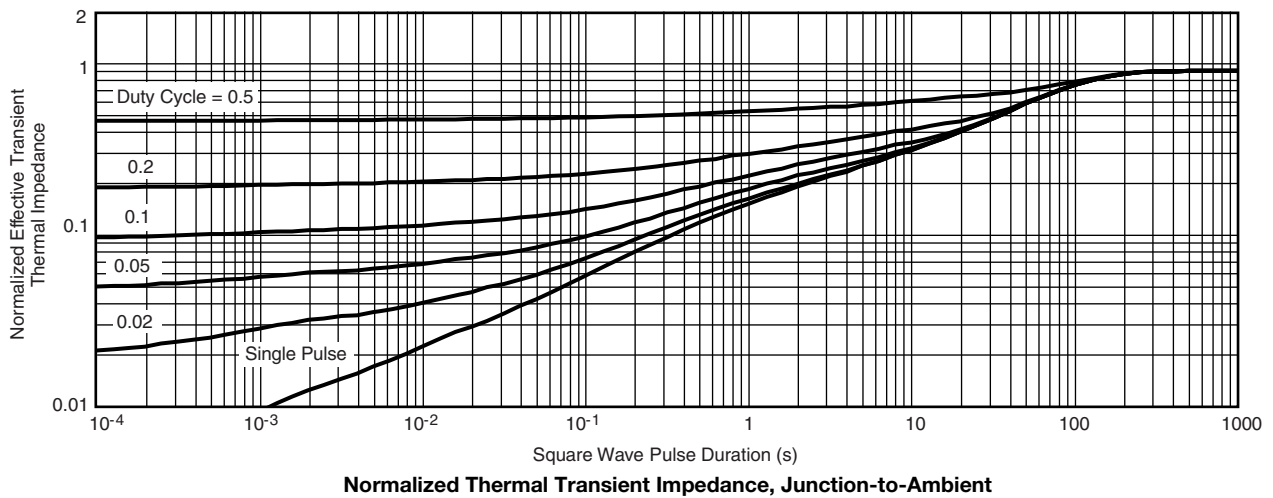
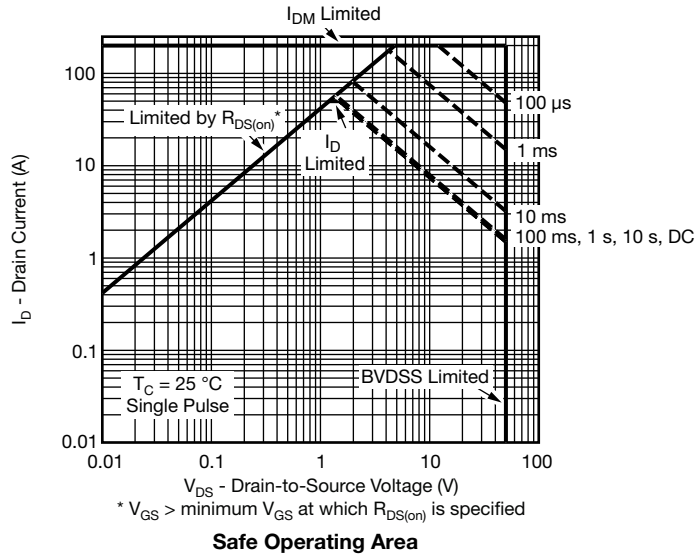


Threshold Voltage

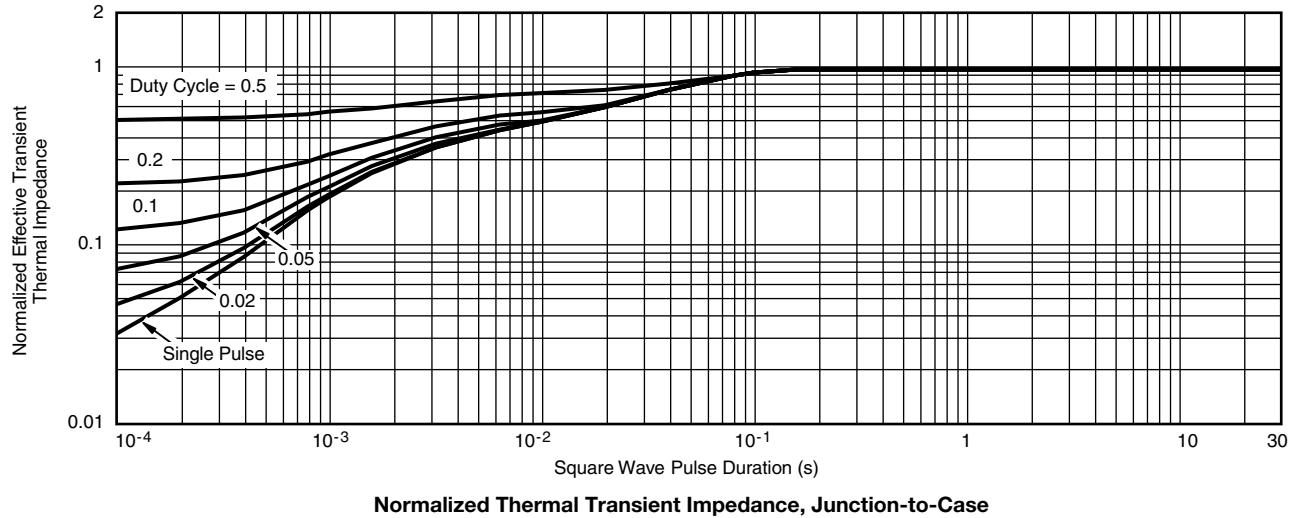


Drain Source Breakdown vs. Junction Temperature

THERMAL RATINGS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise noted)



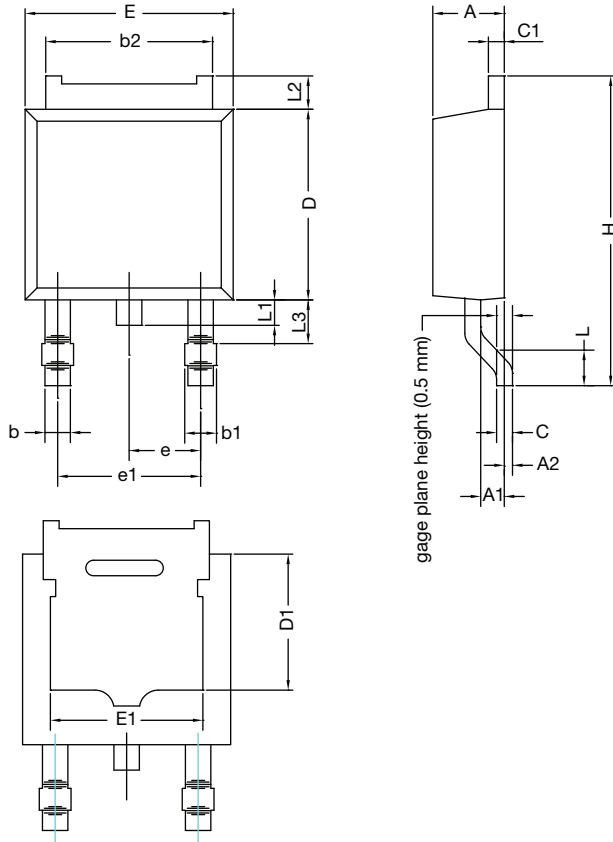
THERMAL RATINGS ($T_A = 25\text{ °C}$, unless otherwise noted)



Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)
 are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

TO-252AA CASE OUTLINE



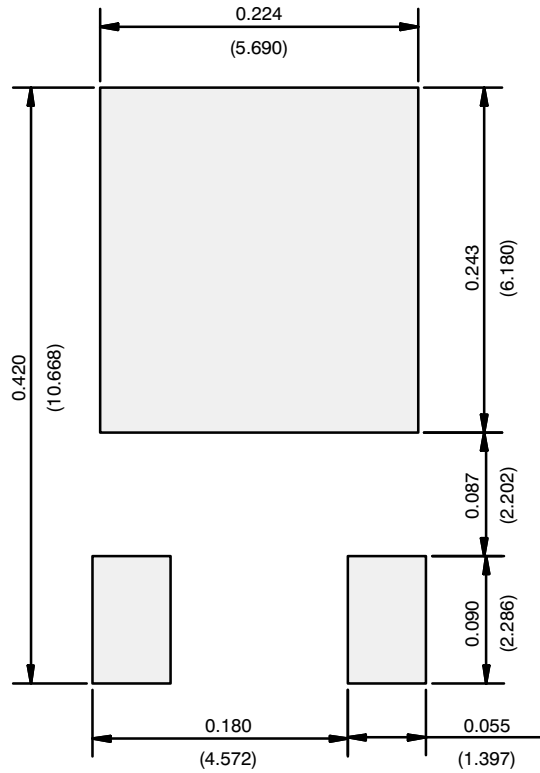
DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.21	2.38	0.087	0.094
A1	0.89	1.14	0.035	0.045
A2	0.030	0.127	0.001	0.005
b	0.71	0.88	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.44	0.206	0.214
C	0.46	0.58	0.018	0.023
C1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
D1	4.10	4.45	0.161	0.175
E	6.48	6.73	0.255	0.265
E1	4.49	5.50	0.177	0.217
e	2.28 BSC		0.090 BSC	
e1	4.57 BSC		0.180 BSC	
H	9.65	10.41	0.380	0.410
L	1.40	1.78	0.055	0.070
L1	0.64	1.02	0.025	0.040
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.040	0.060

ECN: T11-0110-Rev. L, 18-Apr-11
DWG: 5347

Note

- Dimension L3 is for reference only.

RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads
 Dimensions in Inches/(mm)

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